

- Low-loss SAW Filter
- Surface-mount 3.0 x 3.0 x 1.4 mm Package
- Complies with Directive 2002/95/EC (RoHS)

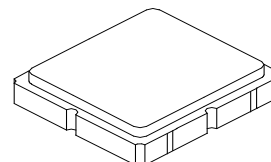


Absolute Maximum Ratings

Rating	Value	Units
Input Power Level	10	dBm
DC Voltage on any Non-ground Terminal	3	V
Operating Temperature Range	-20 to +50	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Solder Reflow Temperature, 10 seconds, 5 cycles maximum	260	°C

SF2177E-1

**1472 MHz
SAW Filter**



SM3030-6

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	F _C			1472		MHz
Insertion Loss, 1452 to 1492 MHz	IL			3.3	4.5	dB
Amplitude Ripple, 1452 to 1492 MHz				1.0	2.0	dB _{P-P}
Attenuation Referenced to 0 dB						
1230 to 1330 MHz			40	55		dB
1570 to 1670 MHz			30	47		
1670 to 1715 MHz			36	48		
Source Impedance	Z _S			50		Ω
Load Impedance	Z _L			50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	983, YWWS					
Standard Reel Quantity	Reel Size 7 Inch	500 Pieces/Reel				
	Reel Size 13 Inch	3000 Pieces/Reel				

Electrical Connections

Connection	Terminals
Input	2
Output	5
Ground	All Others

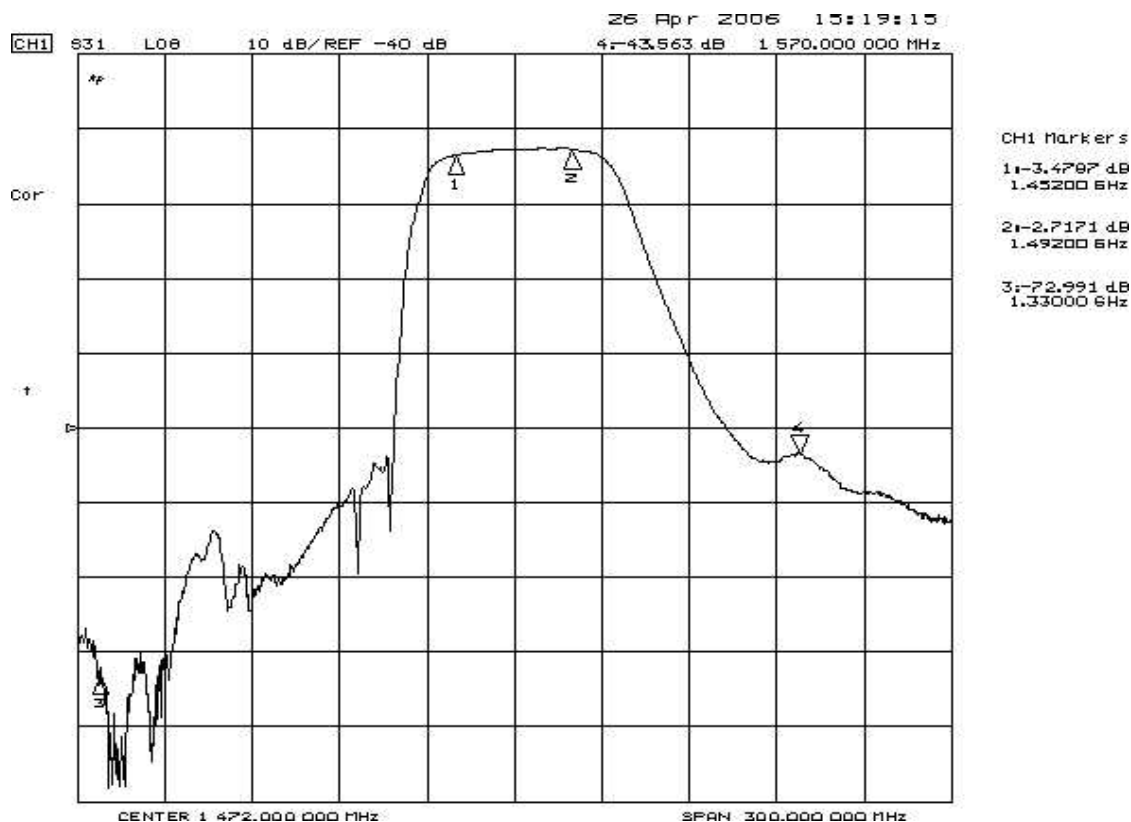


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

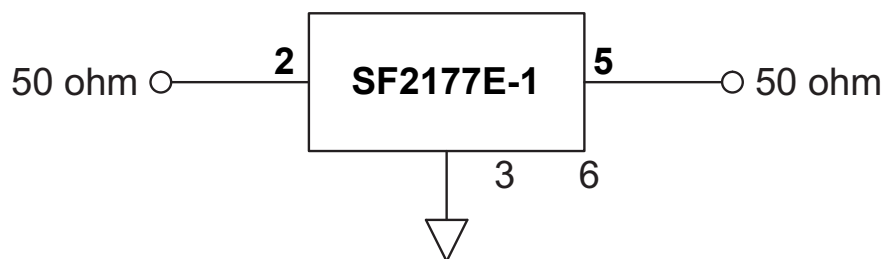
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

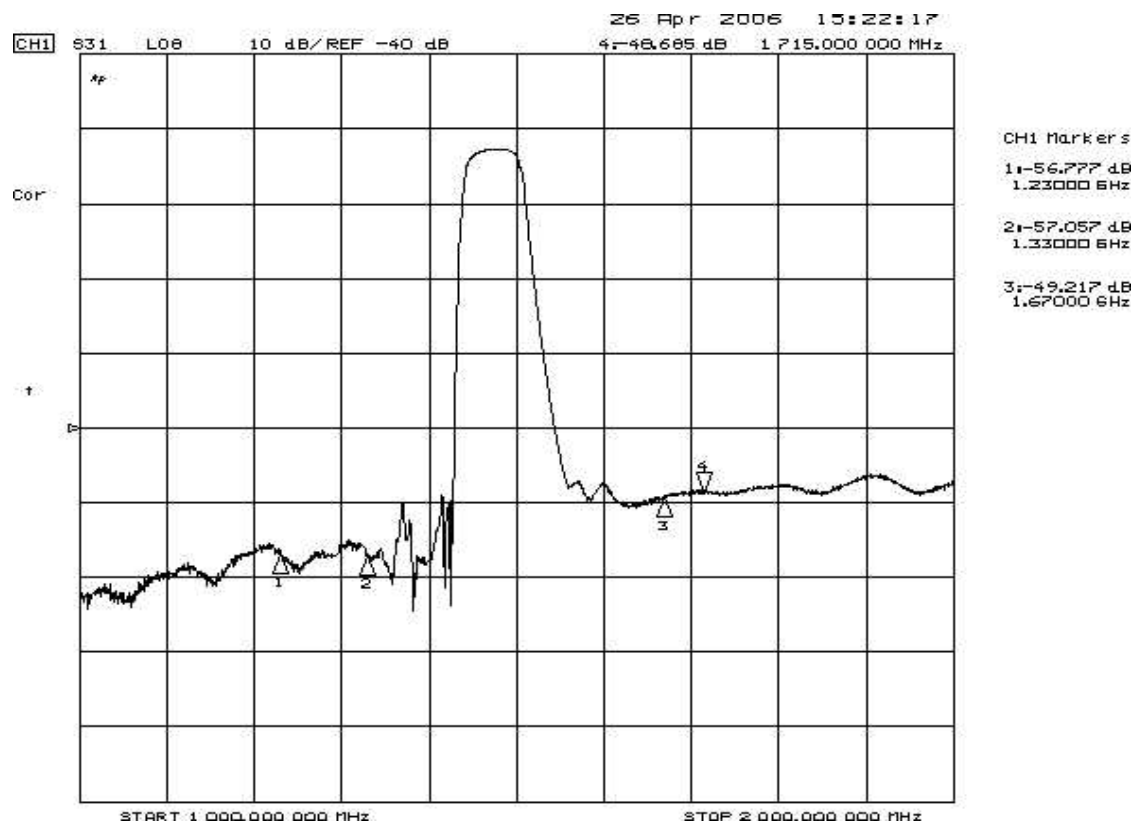
Filter Passband Response



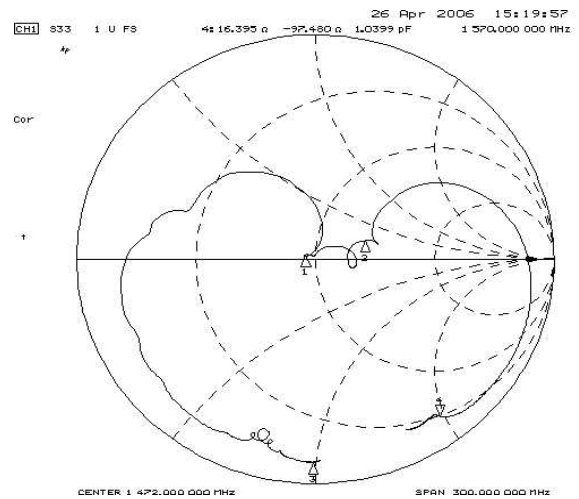
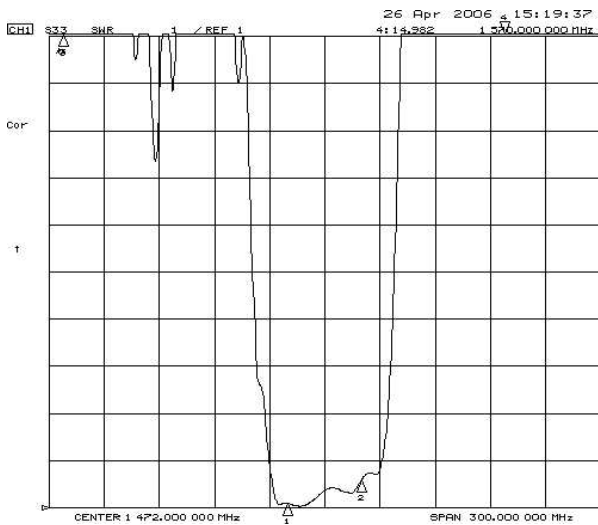
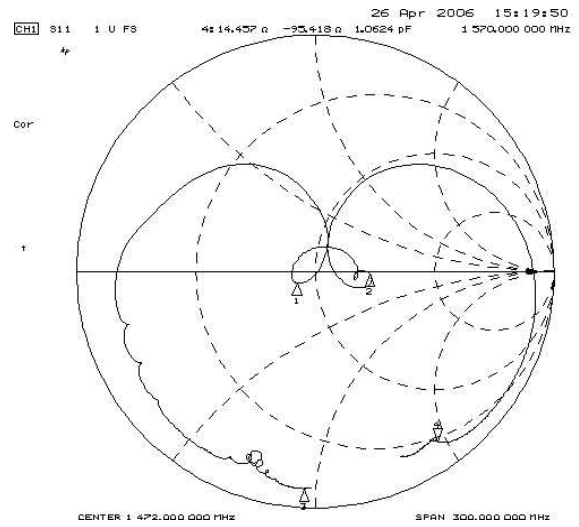
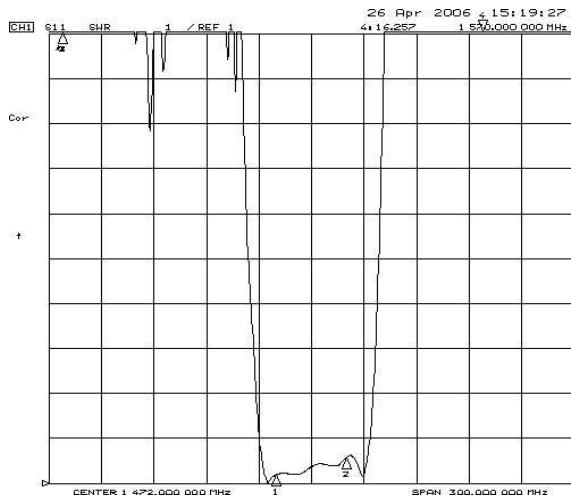
Filter Test Circuit



Filter Broadband Response

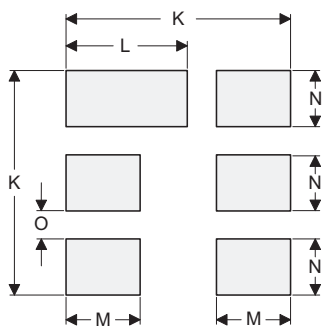
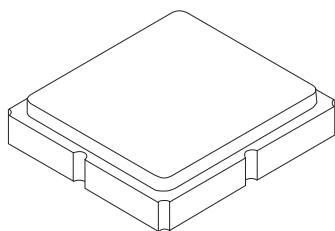


Input and Output VSWR Plots



SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

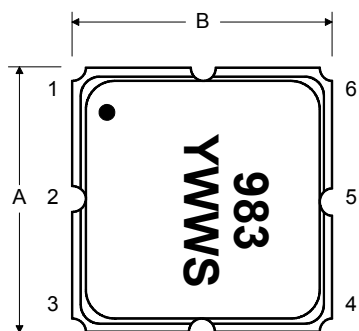
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	2.87	3.00	3.13	0.113	0.118	0.123
B	2.87	3.00	3.13	0.113	0.118	0.123
C	1.12	1.25	1.38	0.044	0.049	0.054
D	0.77	0.90	1.03	0.030	0.035	0.040
E	2.67	2.80	2.93	0.105	0.110	0.115
F	1.47	1.60	1.73	0.058	0.063	0.068
G	0.72	0.85	0.98	0.028	0.033	0.038
H	1.37	1.50	1.63	0.054	0.059	0.064
I	0.47	0.60	0.73	0.019	0.024	0.029
J	1.17	1.30	1.43	0.046	0.051	0.056
K		3.20			0.126	
L		1.70			0.067	
M		1.05			0.041	
N		0.81			0.032	
O		0.38			0.015	

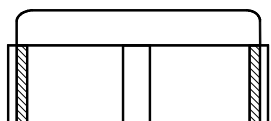
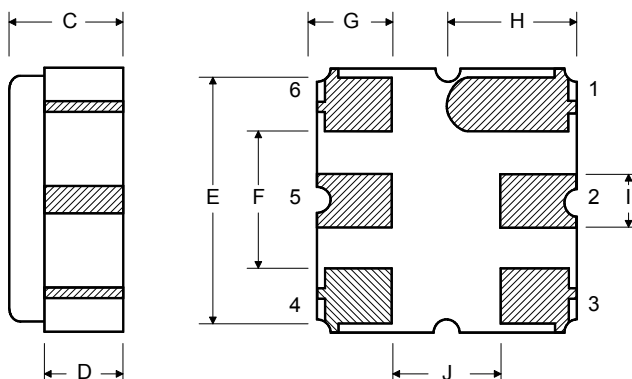
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μ m Gold over 1.27 to 8.89 μ m Nickel
Lid Plating	2.0 to 3.0 μ m Nickel
Body	Al ₂ O ₃ Ceramic
Pb Free	

TOP VIEW

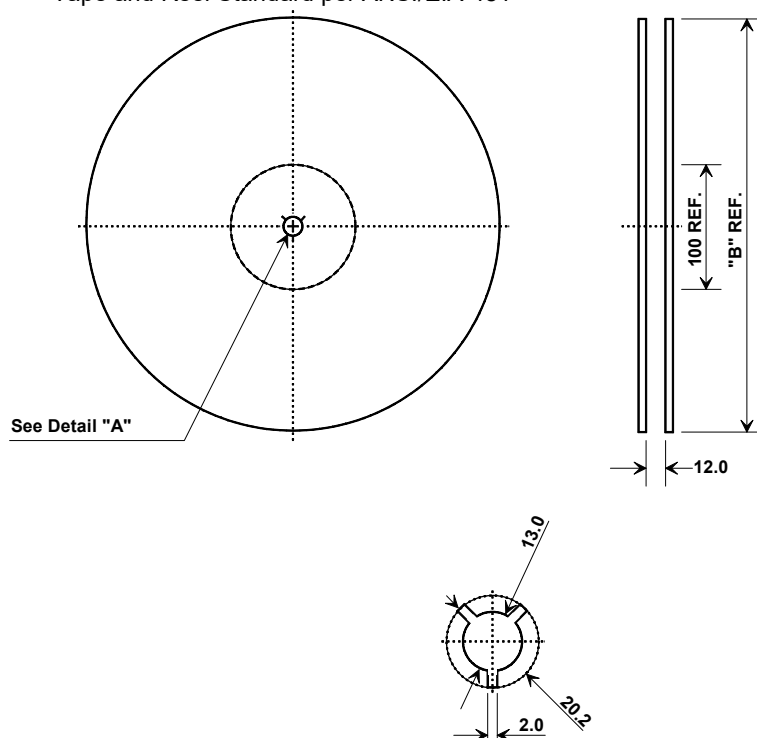


BOTTOM VIEW



Tape and Reel Specifications

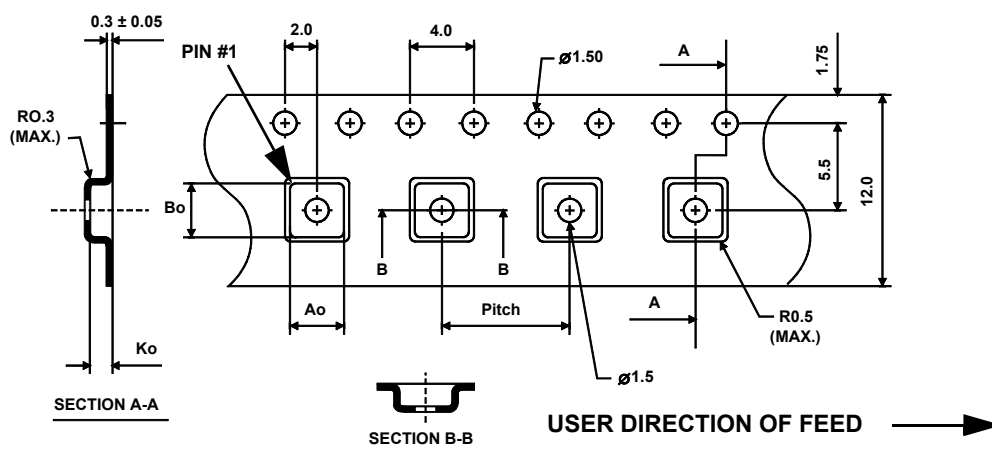
Tape and Reel Standard per ANSI/EIA-481



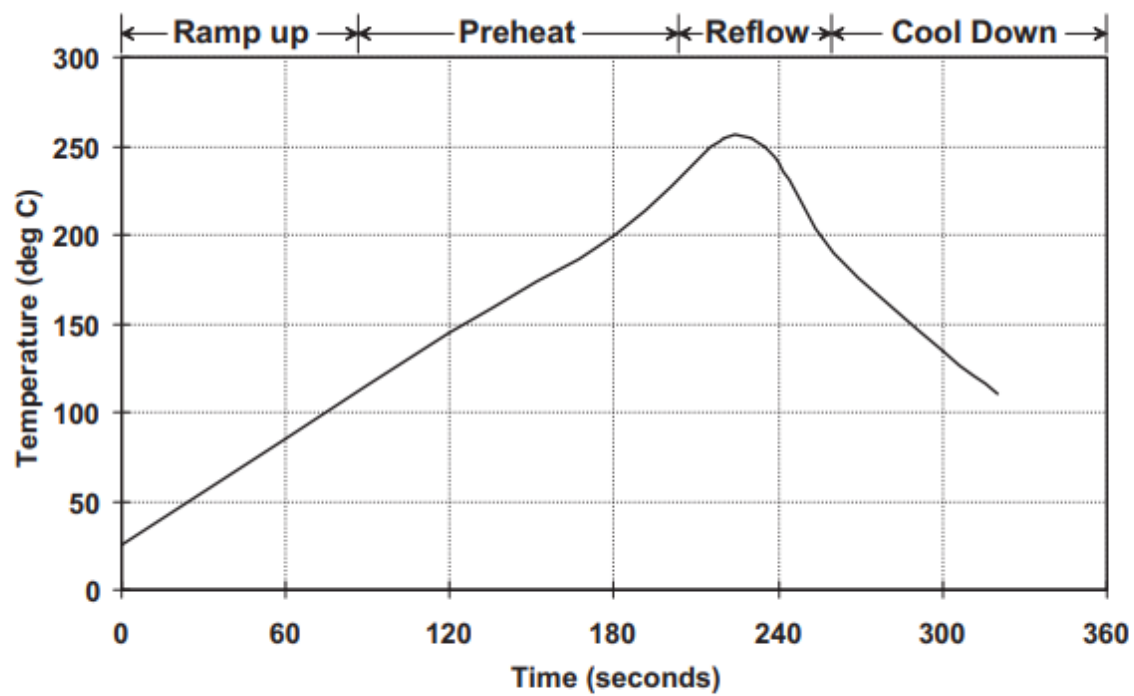
“B”		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	3000

COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.3 mm
Bo	3.3 mm
Ko	1.6 mm
Pitch	8 mm
W	12 mm

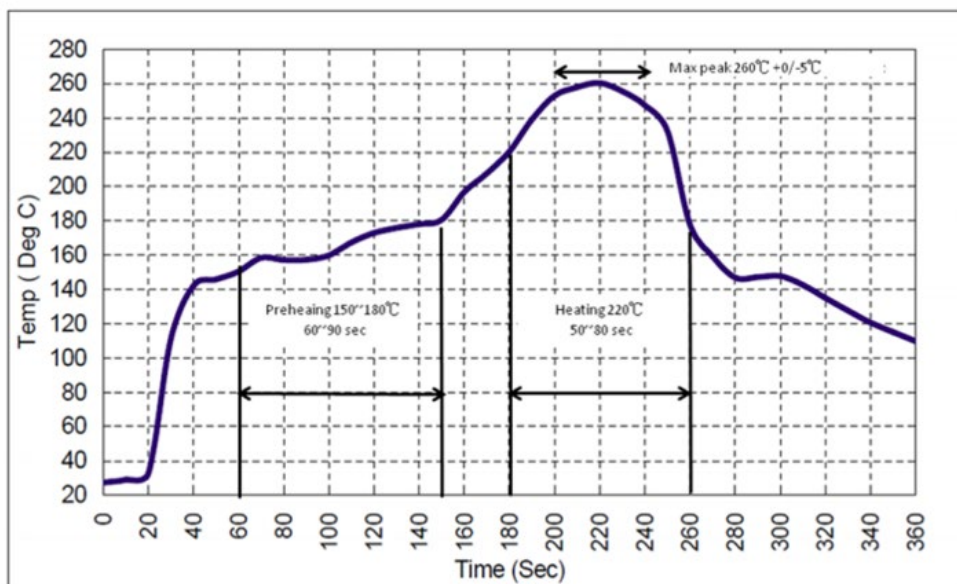


Typical Solder Reflow Profile



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.



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